

### Description

The HSW3415 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

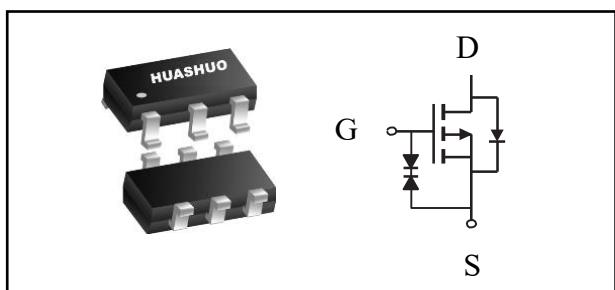
The HSW3415 meet the RoHS and Green Product requirement with full function reliability approved.

### Product Summary

V <sub>DS</sub>	-20	V
R <sub>DS(ON),typ</sub>	29	mΩ
I <sub>D</sub>	-5	A

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- ESD Protect 2.5KV

### SOT23-6L Pin Configurations



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±8	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sub>1</sub>	-5	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -4.5V <sub>1</sub>	-3.9	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-20	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.4	W
P <sub>D</sub> @T <sub>A</sub> =70°C	Total Power Dissipation <sup>3</sup>	0.84	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	100	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =-1mA	---	-0.014	---	V/°C
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sub>2</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A	---	29	35	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3A	---	37	45	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250μA	-0.4	-0.6	-0.9	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	3.95	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	-5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-3A	---	12.8	---	S
Q <sub>g</sub>	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	---	8.4	11	nC
Q <sub>gs</sub>	Gate-Source Charge		---	2.4		
Q <sub>gd</sub>	Gate-Drain Charge		---	1.5		
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-10V, V <sub>GS</sub> =-4.5V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-3A	---	12	---	ns
T <sub>r</sub>	Rise Time		---	9	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	19	---	
T <sub>f</sub>	Fall Time		---	29	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHz	---	755		pF
C <sub>oss</sub>	Output Capacitance		---	113		
C <sub>rss</sub>	Reverse Transfer Capacitance		---	80		

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current <sub>1,4</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-5	A
I <sub>SM</sub>	Pulsed Source Current <sub>2,4</sub>		---	---	-20	A
V <sub>SD</sub>	Diode Forward Voltage <sub>2</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



**HUASHUO**  
SEMICONDUCTOR

**HSW3415**

**P-Ch 20V Fast Switching MOSFETs**

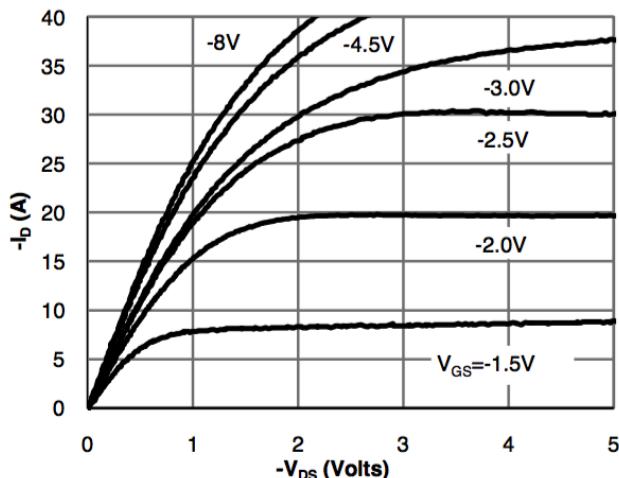


Fig 1: On-Region Characteristics (Note E)

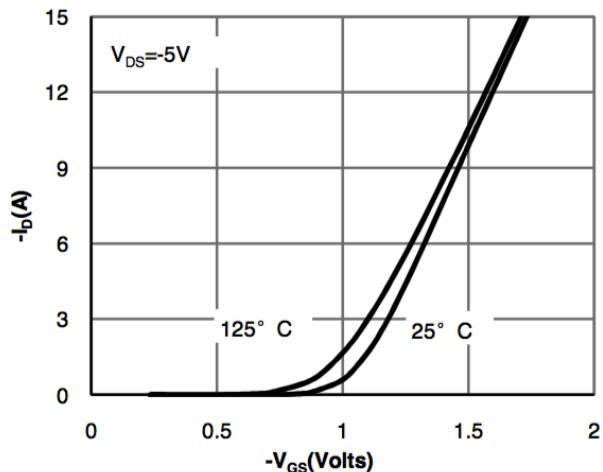


Figure 2: Transfer Characteristics (Note E)

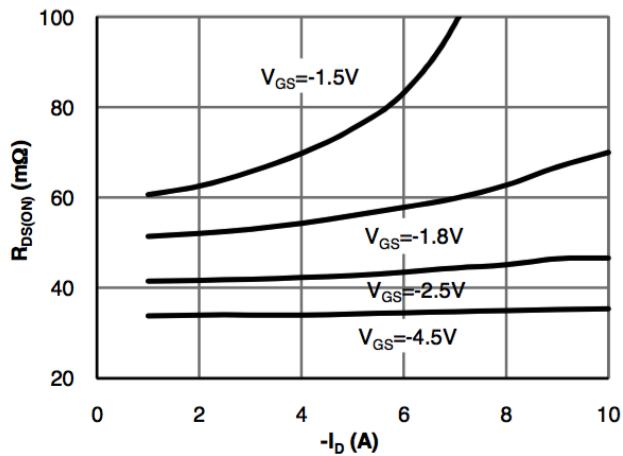


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

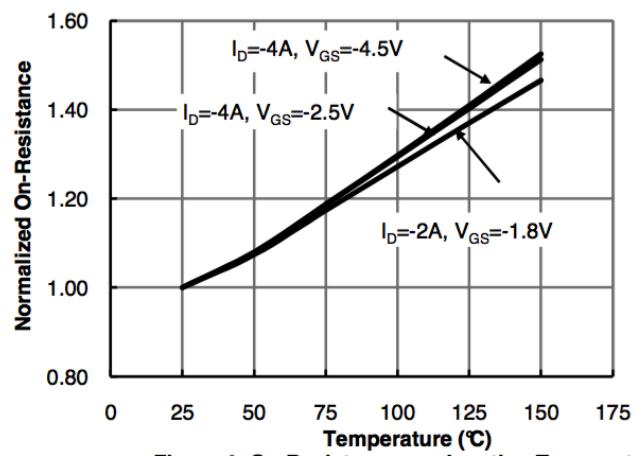


Figure 4: On-Resistance vs. Junction Temperature (Note E)

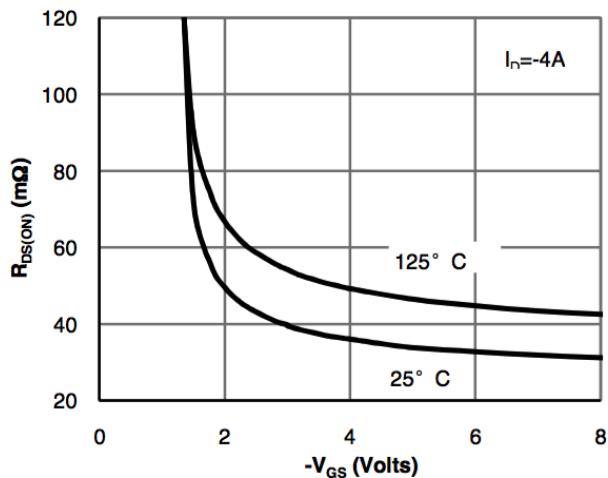


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

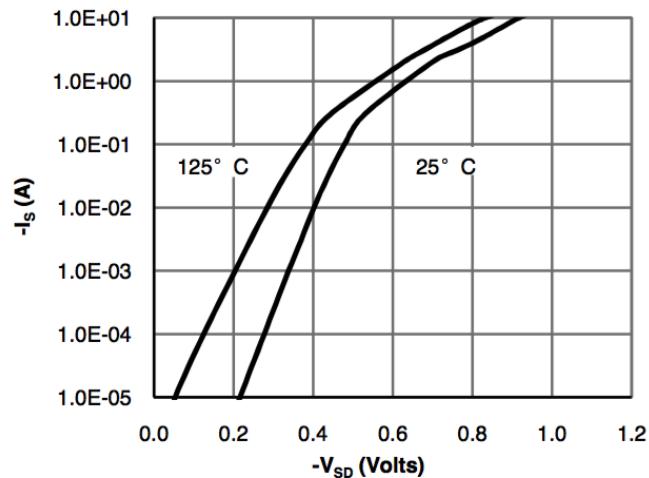
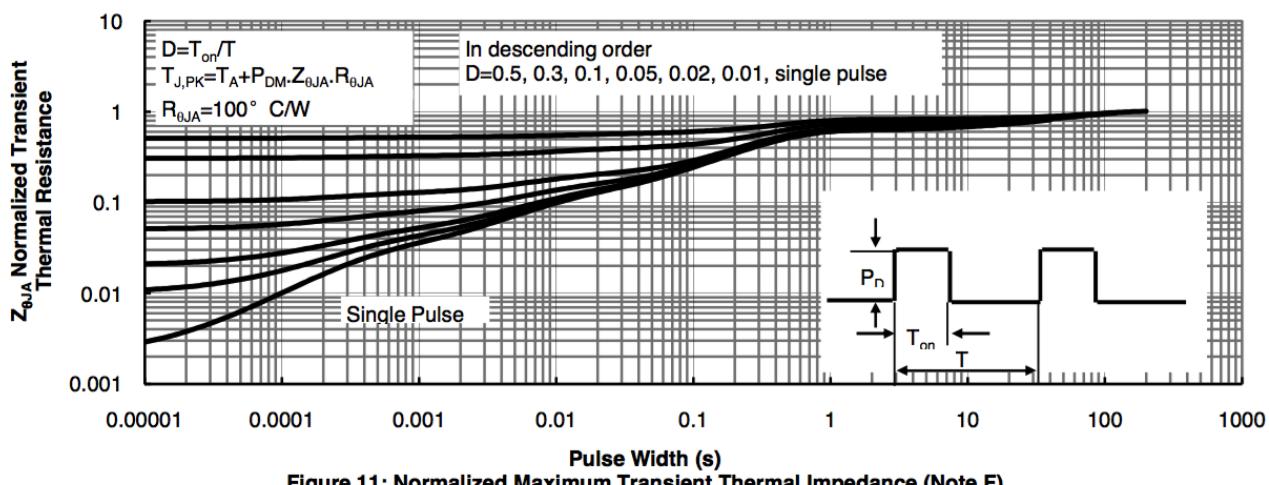
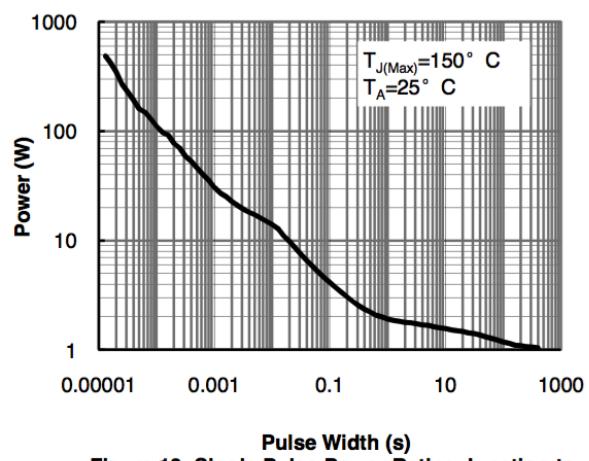
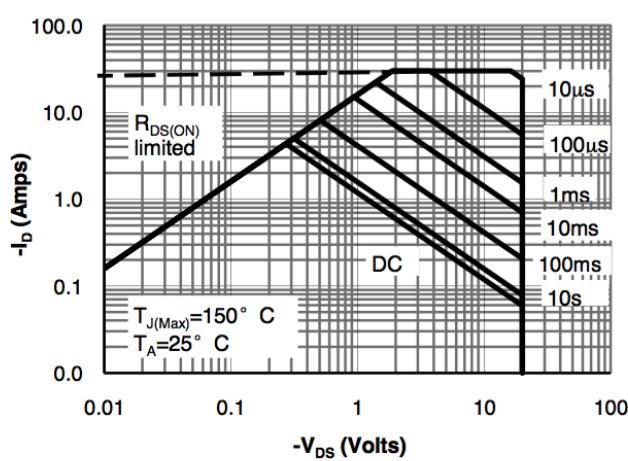
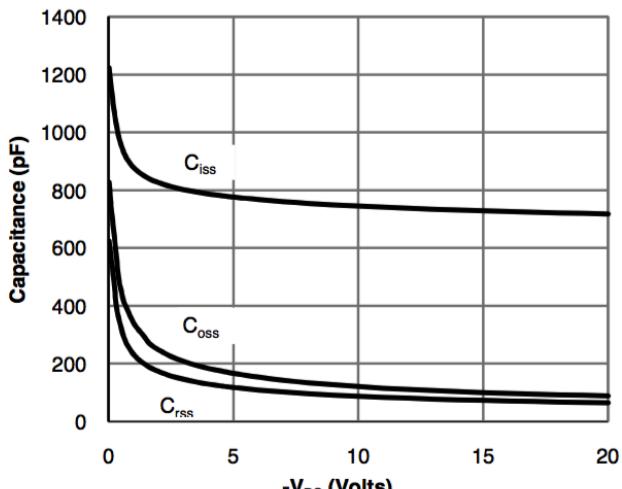
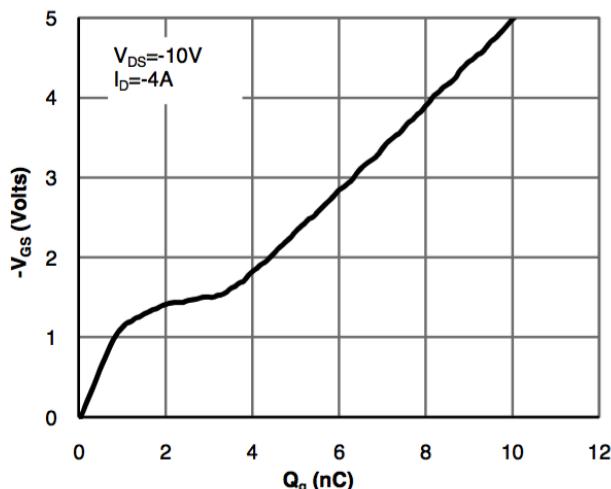


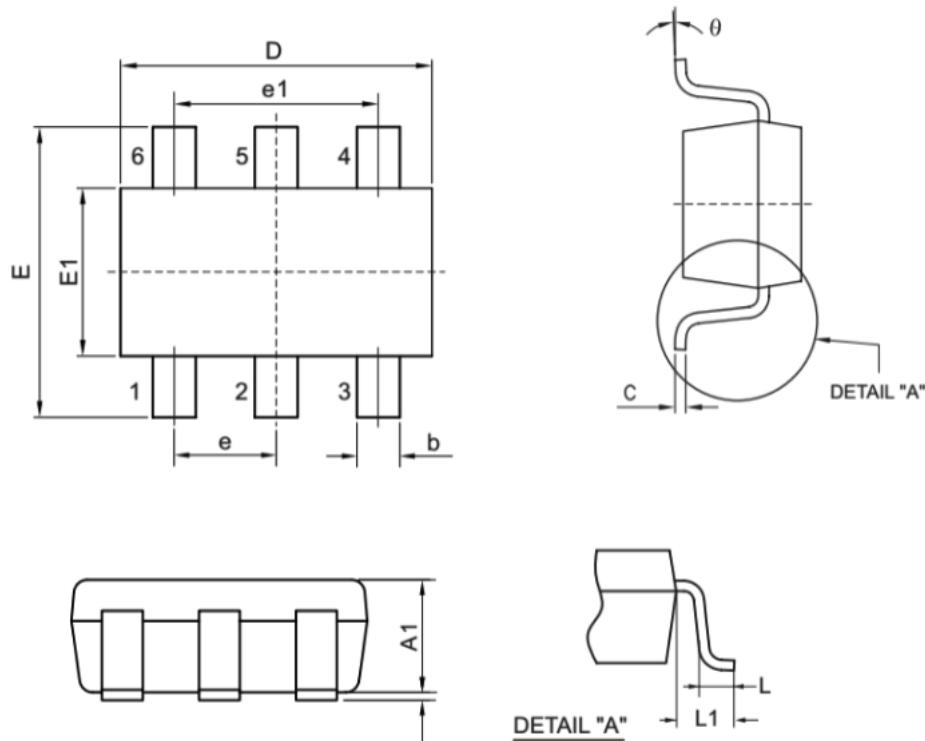
Figure 6: Body-Diode Characteristics (Note E)





## Ordering Information

Part Number	Package code	Packaging
HSW3415	SOT23-6L	3000/Tape&Reel



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
D	2.692	3.099	0.106	0.122
E	2.591	3.000	0.102	0.118
E1	1.397	1.803	0.055	0.071
e	0.950	REF.	0.037	REF.
e1	1.900	REF.	0.075	REF.
b	0.300	0.500	0.012	0.020
C	0.080	0.200	0.003	0.008
A	0.000	0.100	0.000	0.004
A1	0.700	1.200	0.028	0.048
L	0.300	0.600	0.012	0.024
L1	0.600	REF.	0.023	REF.
θ	0°	9°	0°	9°